

Flexible 1-Component Adhesive for electronic applications

EPOXONIC® 71 is a silver-filled, solvent-free, one-component adhesive based on epoxy resin. It features: very high flexibility, long pot life and low chloride content. As a result of its flexibility, **EPOXONIC 71** is especially suited for the adhesion of large die.

Technical Data

- Color silver
- Viscosity at 25°C $\geq 30,000$ mPas
- Viscosity at 23°C ca. 56,000 mPas
- Silver content approx. 71%
- Density 2.89 gm/cc
- Shore Hardness A 37

Handling

- Method of application Dispenser
- Recommended processing temperature 25°C
- Potlife at 25°C (doubling of viscosity) approx. 7 days
- Recommended cure schedule
if necessary, post-cure 45 minutes 120°C plus 2 hrs 140°C
1 to 3 hrs 160°C

Packaging

EPOXONIC® 71 is available in 30 ml cartridges as a frozen product. Other packaging forms are available on request.

Storage Stability

EPOXONIC® 71 should be transported and stored in closed cartridges at $\leq -30^{\circ}\text{C}$. Storage life at this temperature is at least 12 months. For a short time it can be stored at $+4^{\circ}\text{C}$ (refrigerated conditions). At this temperature the storage life is approximately 2 - 3 months.

Quality Assurance

If required, **EPOXONIC® 71** will be supplied with a quality certificate.

Caution

As with all epoxy materials, this product may cause skin irritation. Recommended industrial hygiene procedures should always be followed when handling **EPOXONIC® 71**. Please refer to Material Safety Data Sheet for details.

Disclaimer:

All information herein is based on the present state of knowledge and believed to be reliable. Any suggestions or recommendations are made without liability on our part since we shall have no control over the use of our product. Buyers and users should make their own assessment of this product under their own conditions and for their own requirements.